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(12) **United States Design Patent**
Cai

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(54) **HEADSET**

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(**) Term: **15 Years**

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(52) **U.S. Cl.**
USPC **D14/223**

(58) **Field of Classification Search**
USPC D14/223, 205; D24/106; 381/380, 381, 381/322, 328; 455/90.3, 575.1, 569.1
CPC H04R 1/10; H04R 25/00; H04R 1/1066; H04R 1/1016; H04R 5/0335; H04R 5/033; H04R 1/1091; H04R 1/1083
See application file for complete search history.

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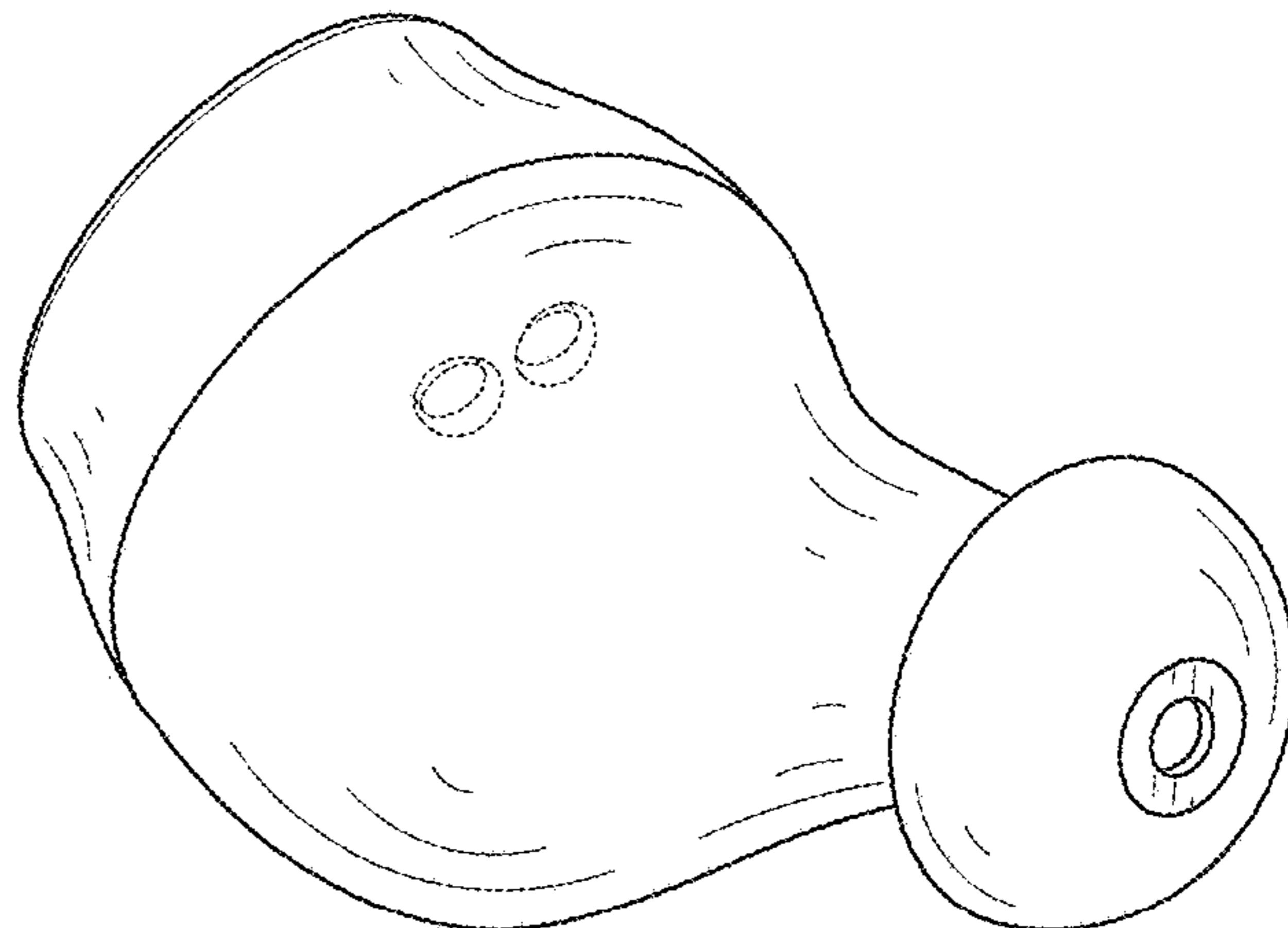
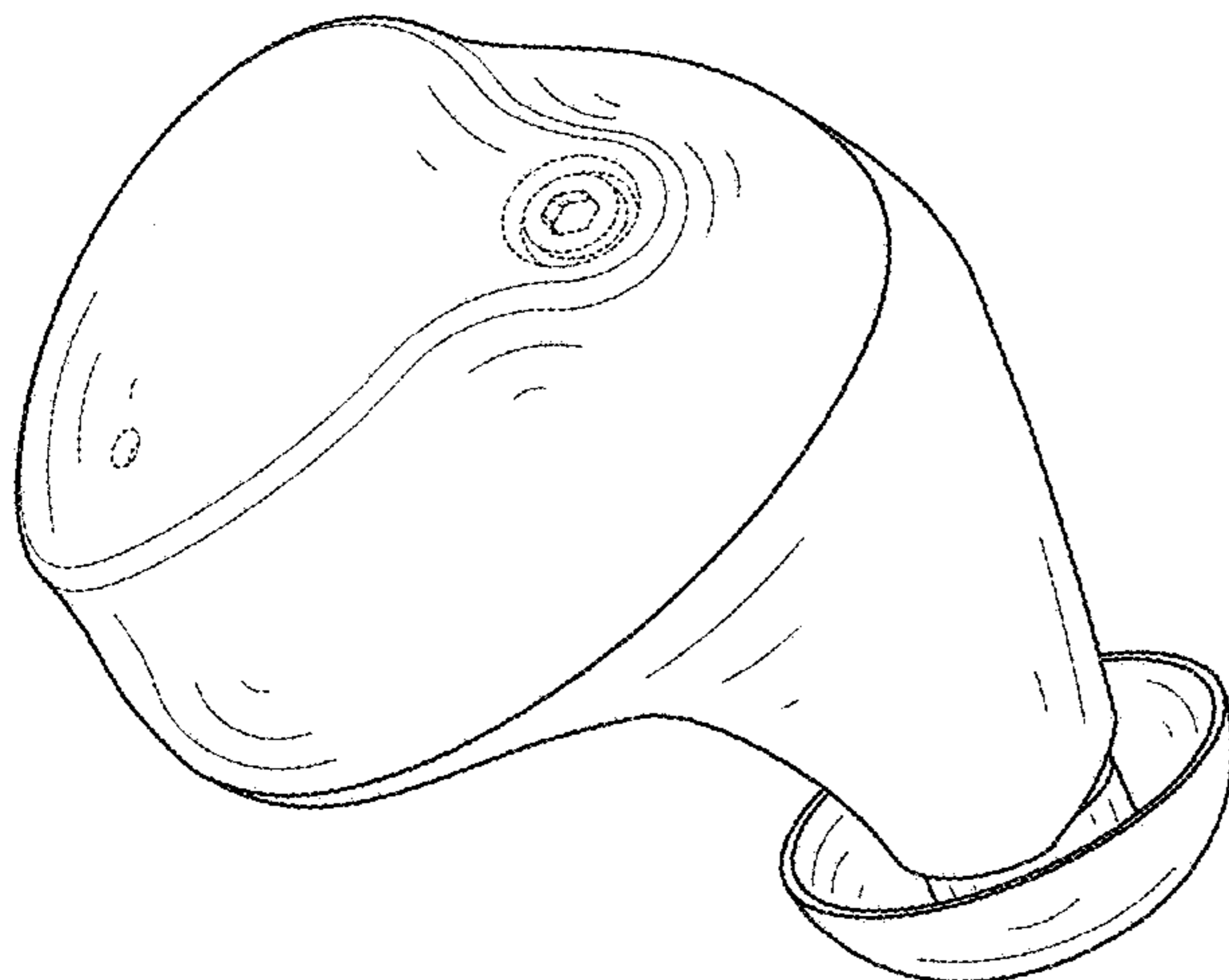
(57) **CLAIM**

The ornamental design for a headset, as shown and described.

DESCRIPTION

FIG. 1 is a front, right, side, top perspective view of a headset showing my new design with one headset shown separately for purposes of illustration;
 FIG. 2 is a rear, left side, bottom perspective view thereof;
 FIG. 3 is a front elevational view thereof;
 FIG. 4 is a rear elevational view thereof;
 FIG. 5 is a left side elevational view thereof;
 FIG. 6 is a right side elevational view thereof;
 FIG. 7 is a top plan view thereof;
 FIG. 8 is a bottom plan view thereof; and,
 FIG. 9 is a top perspective view of at least one headset showing the same when disposed within a storage box.
 The broken lines immediately adjacent to the shaded surface are boundaries, all other broken lines are environment; the broken lines are for illustrative purposes only and form no part of the claimed design.

1 Claim, 9 Drawing Sheets



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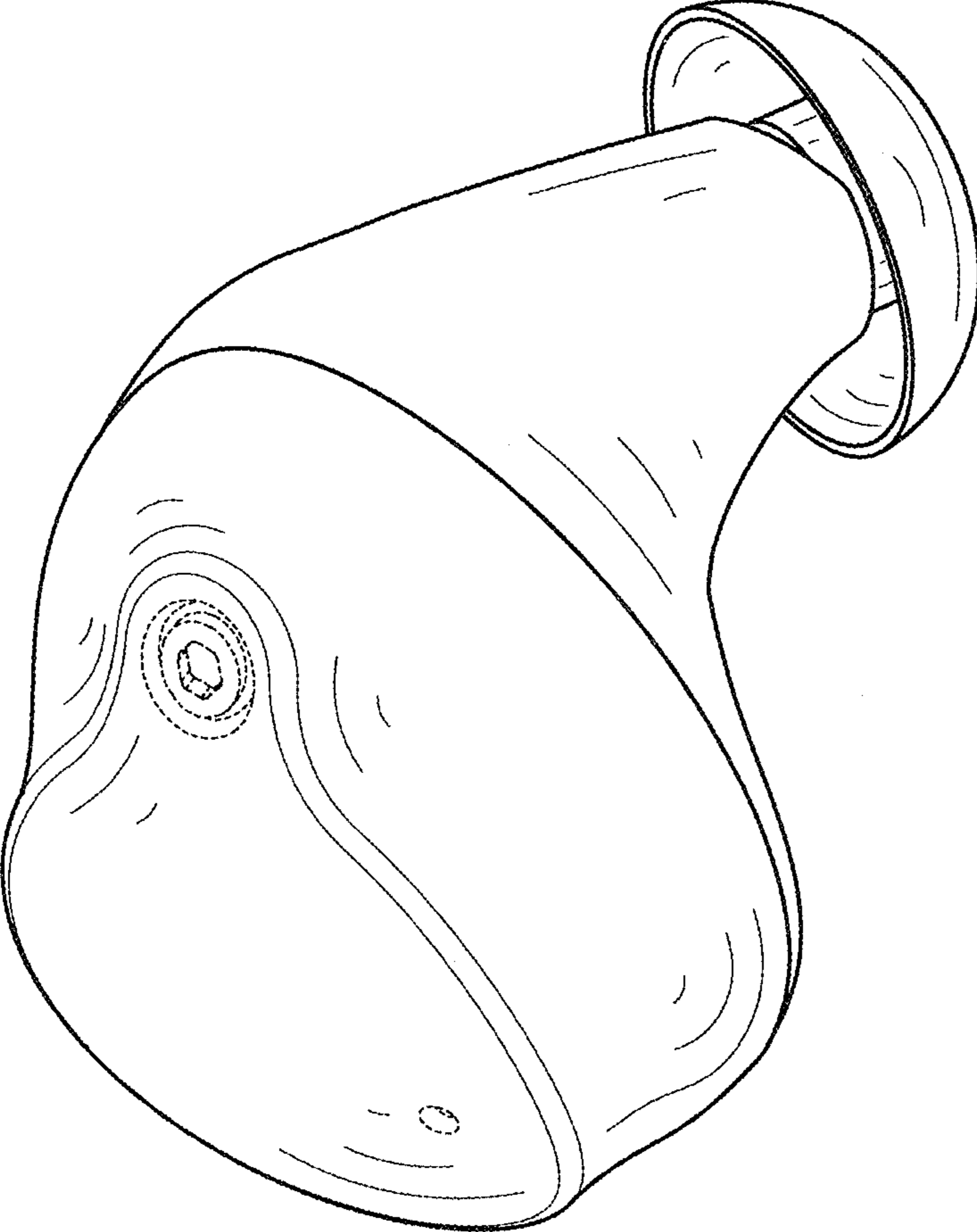


FIG. 1

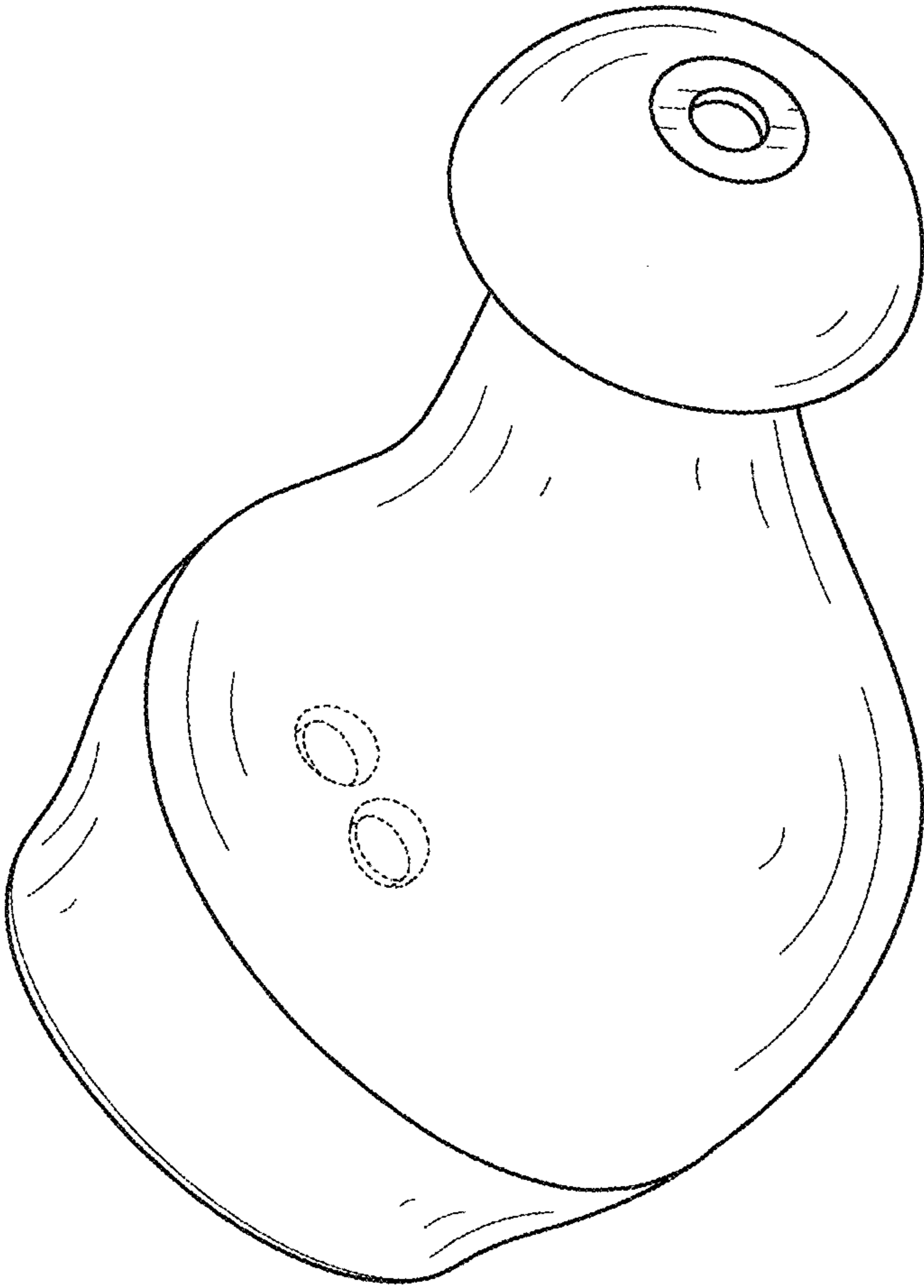


FIG. 2

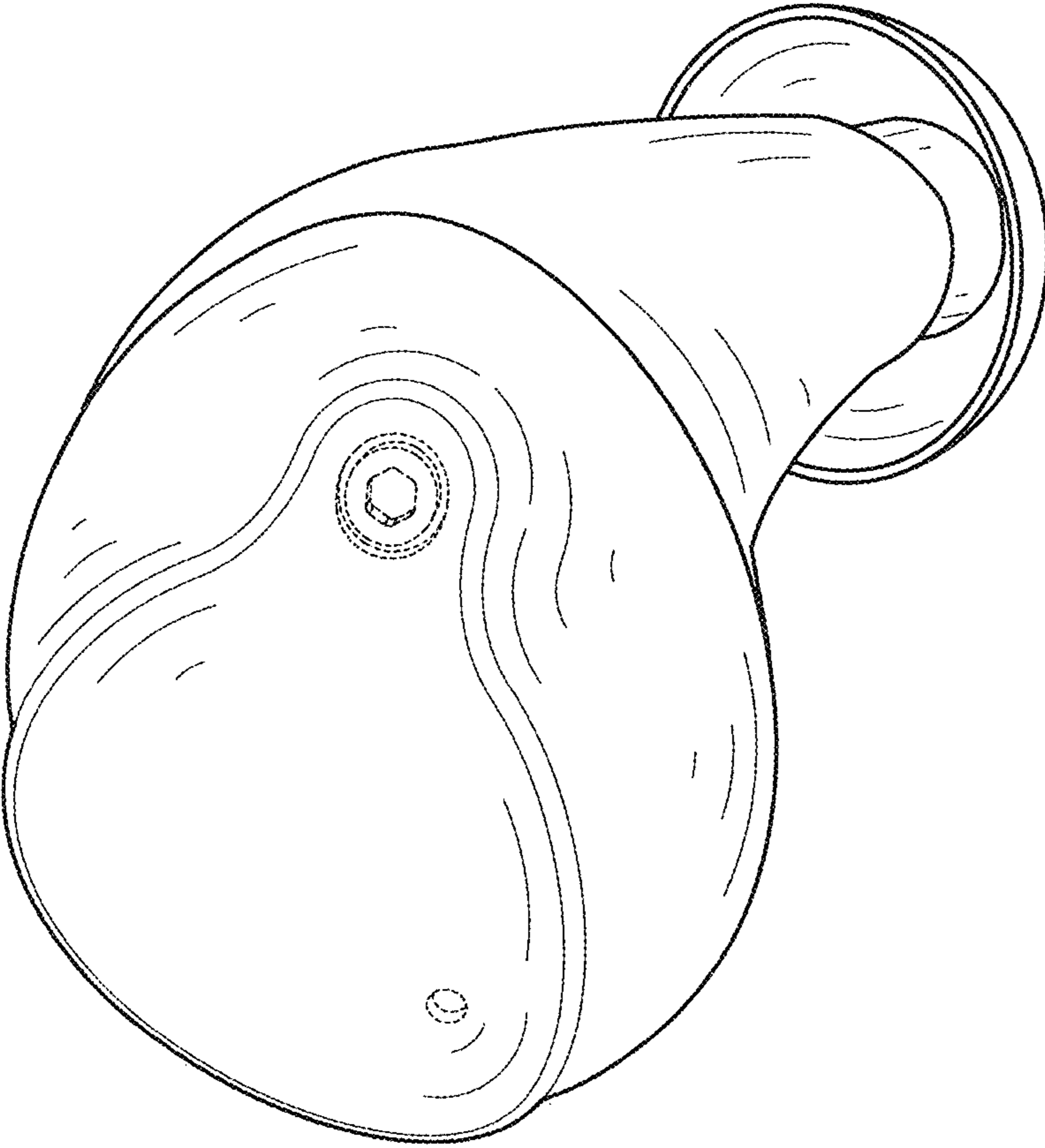


FIG. 3

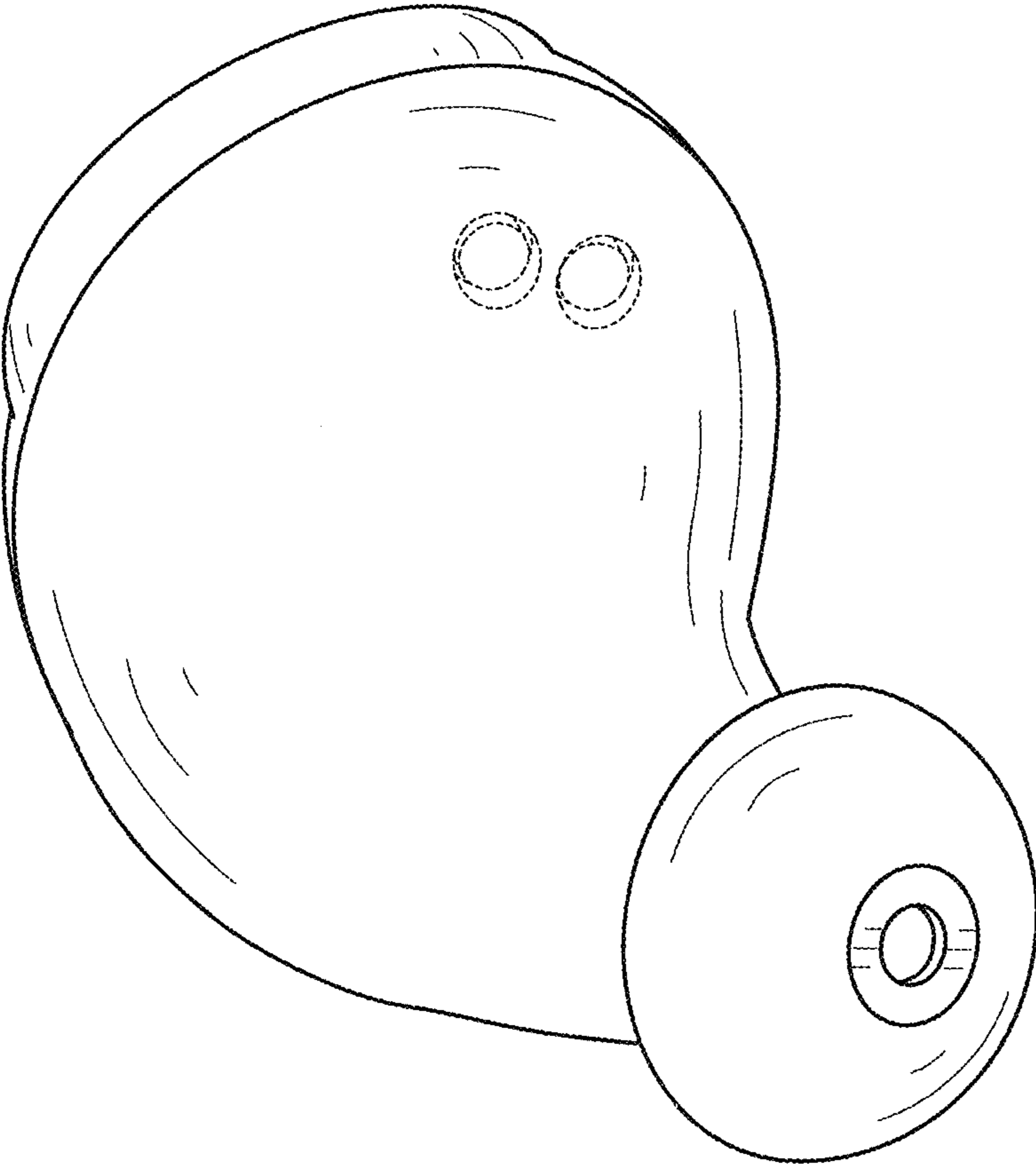


FIG. 4

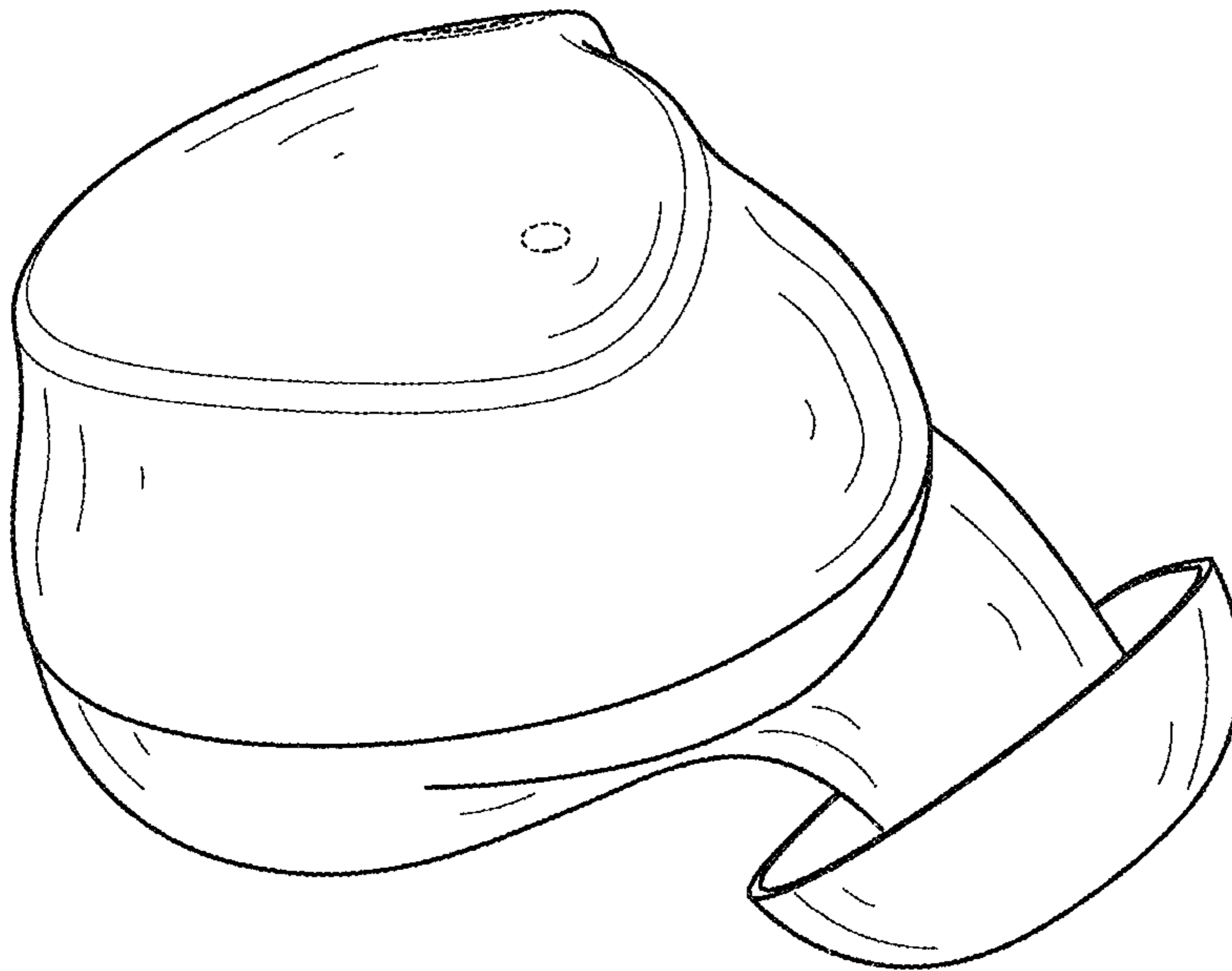


FIG. 5

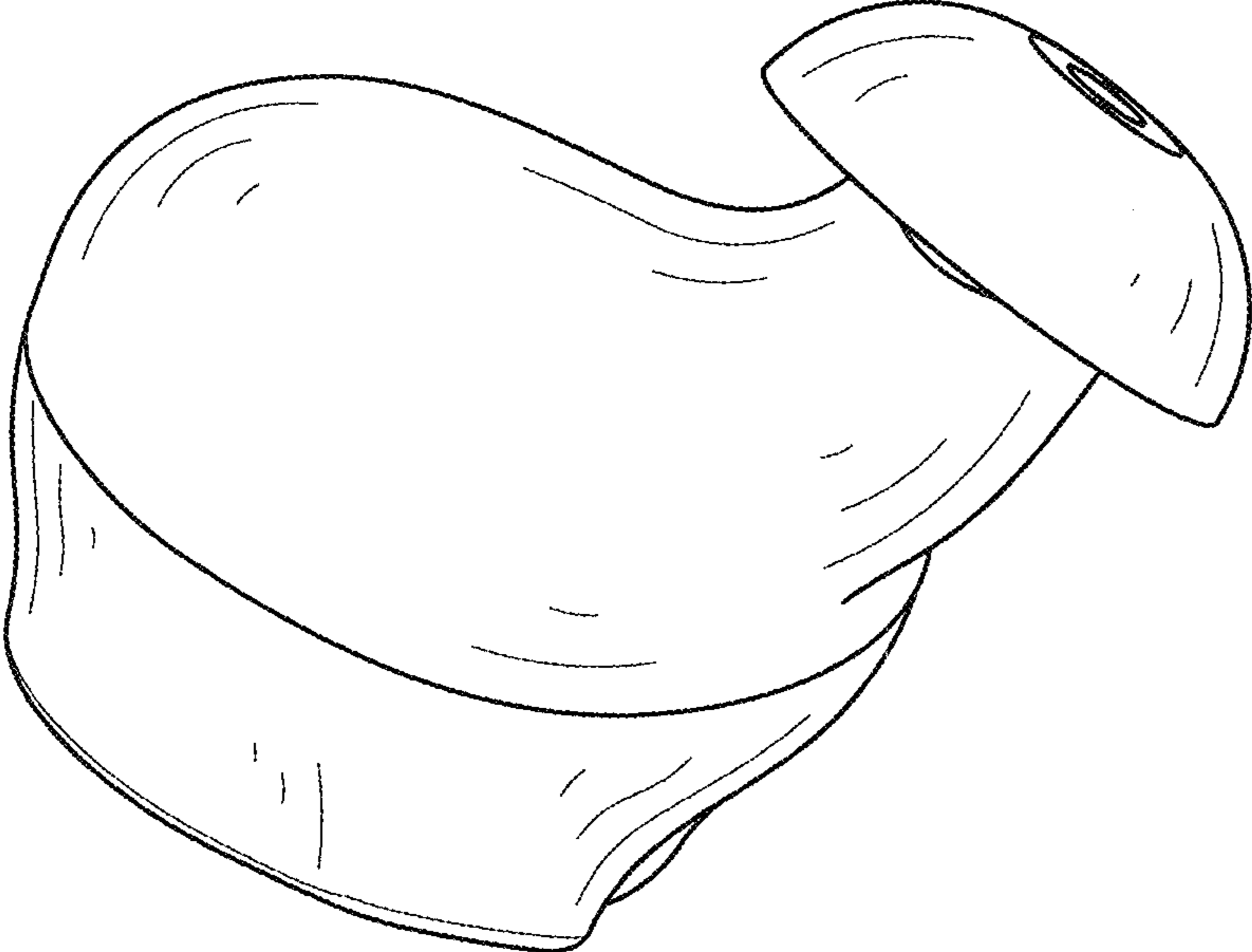


FIG. 6



FIG. 7

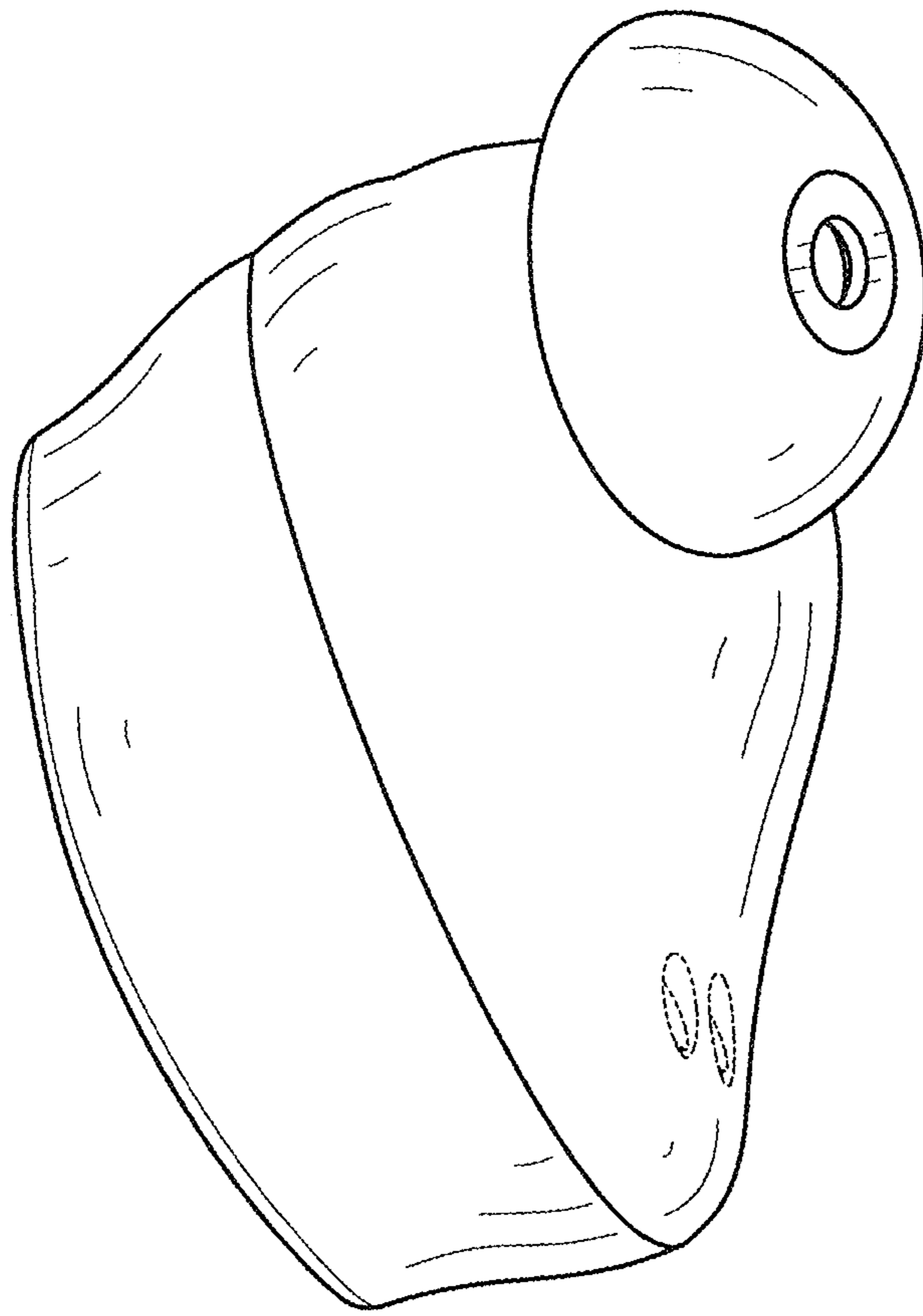


FIG. 8

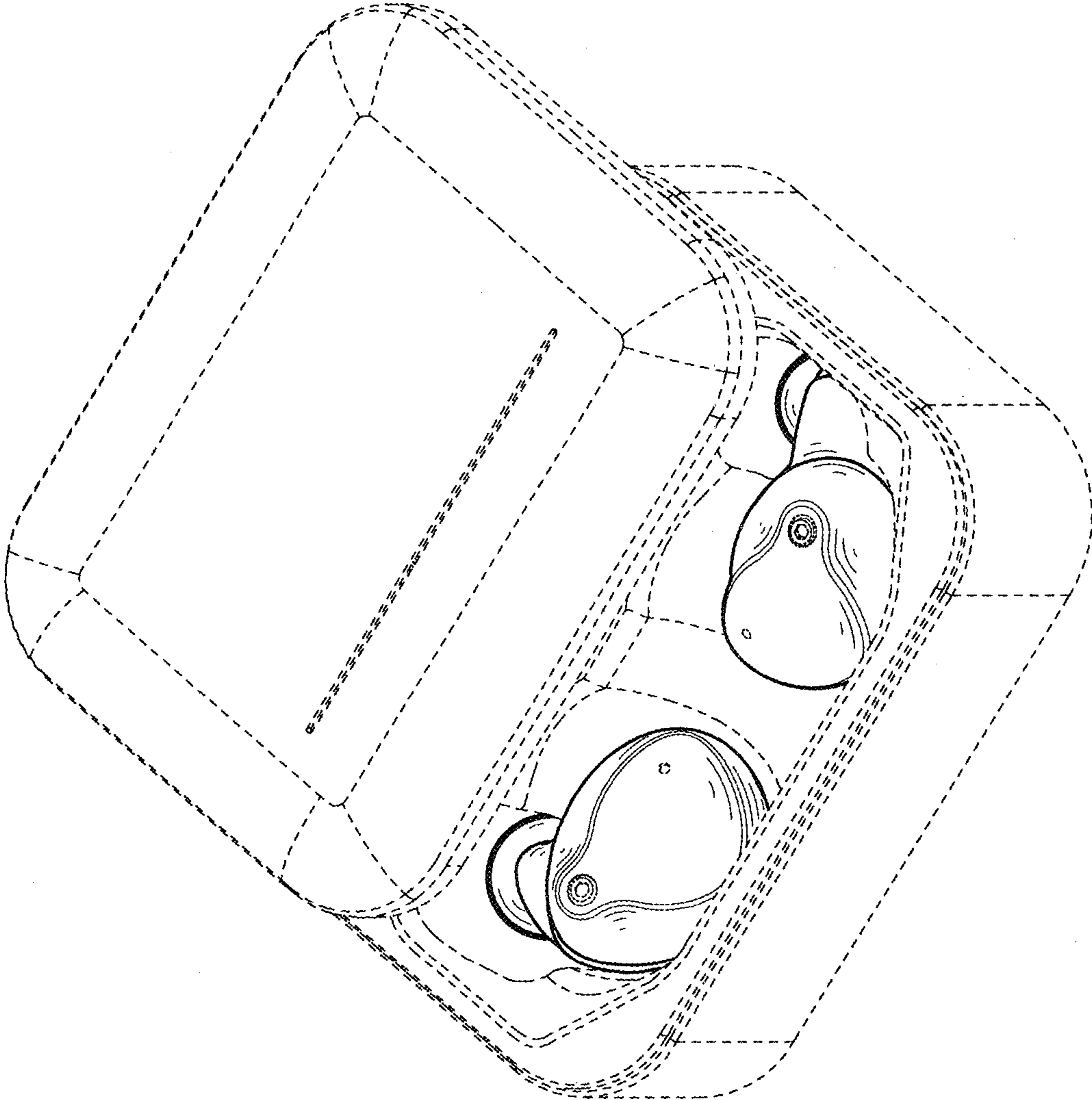


FIG. 9